

A Glimpse on Micro Systems Technologies

The Micro Systems Technologies (MST) Group provides innovative high-tech components and services for technologically advanced industries that demand miniaturisation, exceptional performance and the highest level of reliability. With high-performance components, semiconductor packages and class III assembly, MST offers an integrated supply chain.

We work hand in hand with our customers, along the entire product life cycle. Together, we strive for the best solution in terms of functionality, reliability and cost.

Company structure

Active around the globe, the MST group consists of five technology companies with more than 1,100 employees in three countries, all of whom deliver their customers integrated solutions from design support to series production. Our synchronized operating facilities – located in Switzerland, Germany and the United States – allow us to be present worldwide and maintain global business relationships.

Industries

Offering our customers long-time experiences and outstanding expertise in various industries, the MST companies are specialized in the fields of aerospace & aviation, high-rel industry, healthcare & life sciences, telecommunication and industrial electronics.

Performance

We always deliver products and services with the highest quality while following stringent requirements and processes. Additionally, all our processes and materials assure 100% traceability. The MST companies are certified according to the standards ISO 13485 and/or ISO 9001 and/or ISO 9100.

Contact Data:

Micro Systems Technologies
Management GmbH
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12359 Berlin – Germany
info@mst.com

For more information visit the MST showroom and discover our product offerings.





 Sales  Factory

A Global Footprint with Five Fabrication Sites

> 1,100 Employees

> 200 Engineers

> 25,000 m² Manufacturing Space



DYCONEX AG
Bassersdorf, Switzerland

- Rigid IC substrates and Ultra-HDI boards
- Flexible polyimide boards
- Liquid Crystal Polymer (LCP)

Micro Systems Engineering GmbH
Berg, Germany

- LTCC & HTCC substrates + assembly
- Semiconductor packaging

Micro Systems Engineering, Inc.
Lake Oswego, Oregon, USA

- Class III electronic & device assembly

LITRONIK Batterie-technologie GmbH
Pirna, Germany

- Primary batteries

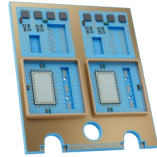
Micro Connect Technologies
Nuremberg, Germany

- Hermetic feedthroughs

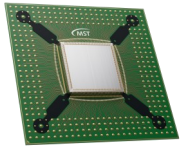
High Performance Components



Flexible Polyimide and LCP boards



Ceramic substrates



Rigid IC substrates and



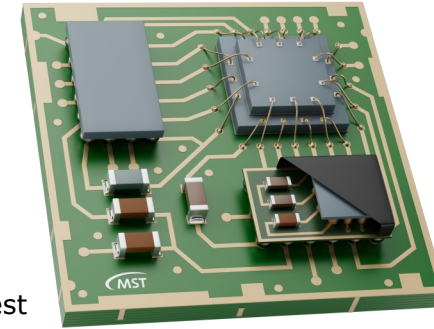
Batteries & feedthroughs

Semiconductor Packaging

Flip Chip & CSP Attach

Singulation, Marking & Traceability

SMT Assembly, Inspection & Test



Wire-bonding & Stacked-Die

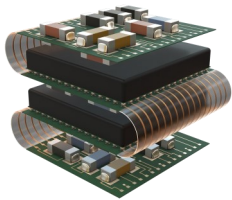
System-in-Package

Transfer Molding, Encapsulation, Housing

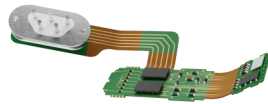
Package Design & Substrates

MST One Stop Shop

Electronic Design & Manufacturing



Miniaturized Electronic Assembly



Class III Electronic Assembly



Class III Device Assembly



Flexible Devices

Product Lifecycle Management



Design for X Validation



Scalability Serial Fabrication



Concept Feasibility Prototyping



Safe Launch



Supply Chain Improvement